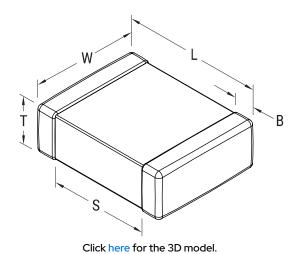


C1812C132J2TAC7210

SMD Comm X8G HT150C, Ceramic, 1,300 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

ensions		Specificatio
Size	1812	Capacitance
	4.5mm +/-0.3mm	Measureme
	3.2mm +/-0.3mm	Tolerance
	1mm +/-0.10mm	Voltage DC
	2.3mm MIN	Dielectric W
	0.6mm +/-0.35mm	Temperature
		Temp. Coef

Packaging Specifications		
Packaging		

Packaging Quantity

Dime Chip L W T S B

> T&R, 330mm, Plastic Tape 4000

Specifications	
Capacitance	1,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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